

219.40446X00



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane LEBONHEUR ET AL.

Serial No.: 09/964,709

Filing Date: September 28, 2001

For: METHOD OF IMPROVING THERMAL PERFORMANCE IN
FLIP CHIP/INTEGRAL HEAT SPREADER PACKAGES USING
LOW MODULUS THERMAL INTERFACE MATERIAL

Examiner: Alonzo Chambliss

Art Unit: 2827

TC 2800 MAIL ROOM

DEC - 3 2002

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AMENDMENT

03/12/2003 JMC:111 0 00000004 012135 09964709
Assistant Commissioner for Patents
01 FC:1201 Washington, D.C. 20231

November 29, 2002

Sir:

The following amendments and remarks are submitted in the above-identified application in response to the Office Action mailed August 28, 2002.

IN THE DRAWINGS:

By a separate Proposed Drawing Correction filed herewith it is proposed to correct the location of a lead line in Figure 1 of the drawings as shown on the copy of Figure 1 attached to the Proposed Drawing Correction.

12/02/2002 SDENB081 00000088 09964709

01 FC:1201

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